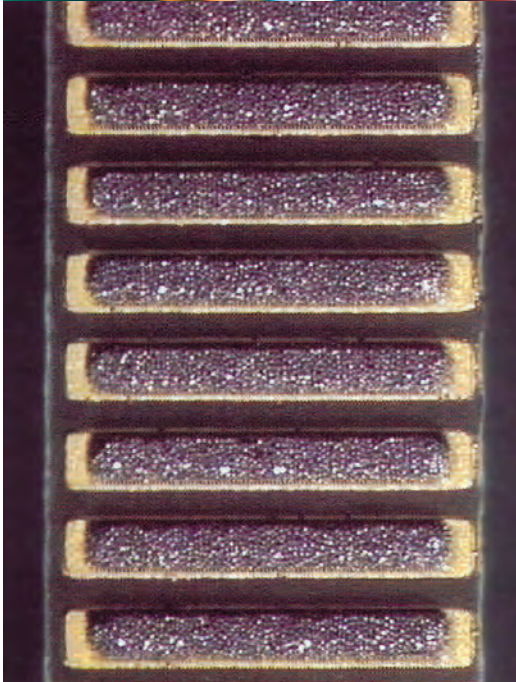




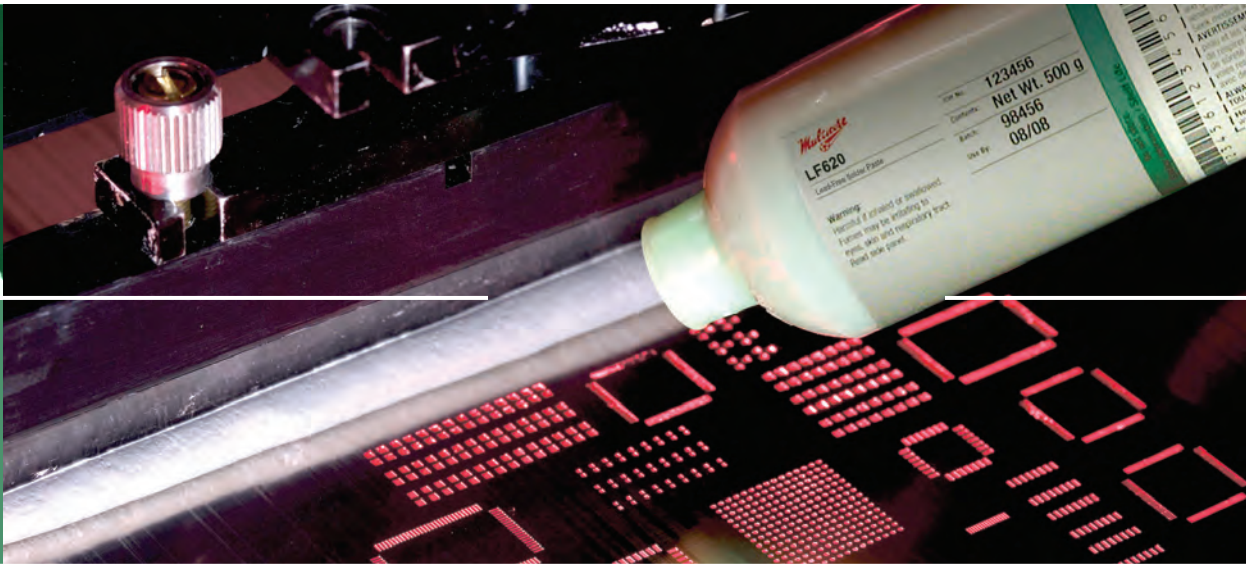
Multicore® LF620™

Halide-free, no-clean, lead-free solder paste



Manufacturers who want a lead-free solder paste that delivers the “best of the best” need look no further than Multicore® LF620™. With long open and abandon times, a broad process window, excellent humidity resistance, ultra-low voiding, zero hot slump and outstanding long-term reliability in a lead-free, halide-free, no-clean formulation, Multicore® LF620™ delivers it all. What’s more, this robust solder paste is capable of printing down to 0.4mm pitch QFP and 0.4mm CSP devices, and has outstanding solderability on a wide range of surface finishes including Nickel/Gold, Immersion Tin, Immersion Silver and OSP Copper.





Henkel's Multicore® LF620™ solder paste is designed for applications that require excellent printability at low speeds and high speeds, with “brick-like” print definition requirements. It is ideally suited for high throughput production, where yield consistency on print deposits is key.

Application Advantages

- Less waste on production line (paste has extensive abandon time and work-life on the printer)
- Increases customer confidence in process control due to solder paste topography consistency when small components are placed
- Suitability for 0.4mm CSP apertures and above encourages customer to embrace technology advancements
- High reliability solder joints: low voiding due to excellent wetting, and minimal hot slump
- Extended tack time helps overcome process delays that may occur on production lines

Product Attribute

Process Benefits

Wide printing process window	4 hours between print abandon time on small CSP apertures Print speed capability up to 150mm/s Excellent print definition Print down to 0.4mm pitch with type 4 powder
Excellent coalescence after 8 hours exposure to 23°C/50%RH	Reduced process variation due to environmental factors, a particular advantage in high temperature/humidity conditions
Negligible hot slump	Minimizes bridging, mid-chip solder balling and links to low void incidence
Colorless and pin-testable residues	Improves speed and ease of post reflow inspection
Low voiding	Reduced risk of bridging on small pitch CSPs and BGAs. Reduced risk of decreased joint reliability
Flux classification by J-STD-004	Halide-free ROL0

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